



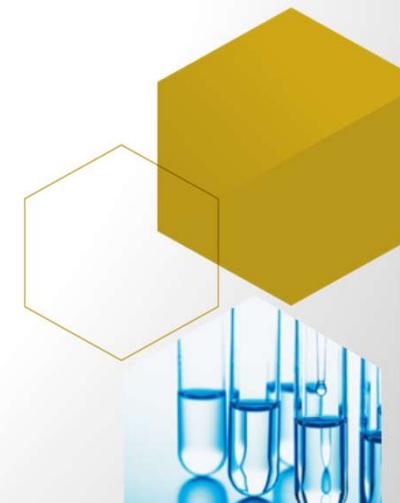
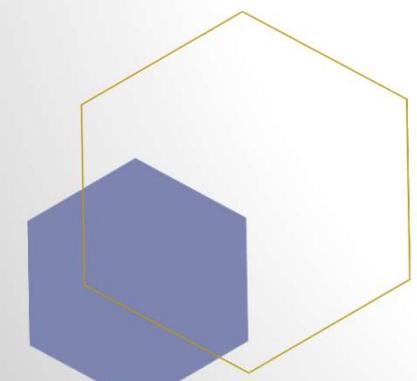
Financial Results for the Third Quarter Ended December 31, 2025

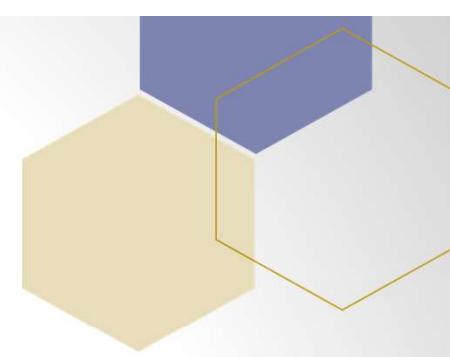
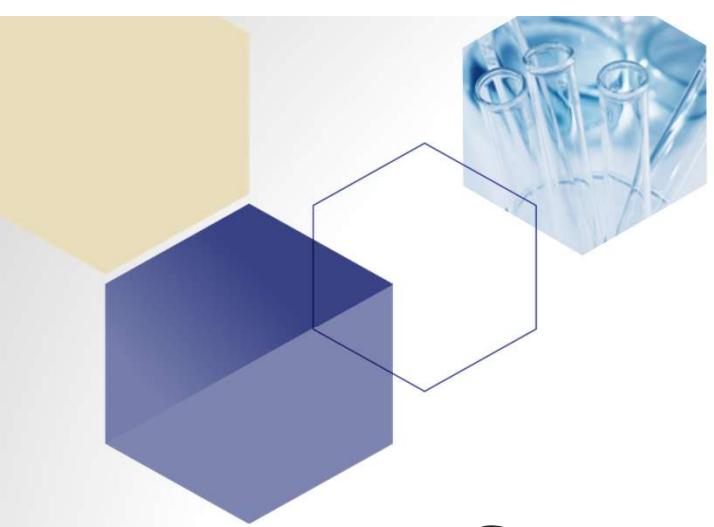


JAPAN PURE CHEMICAL CO.,LTD.

Securities Code: 4973

January 26, 2026

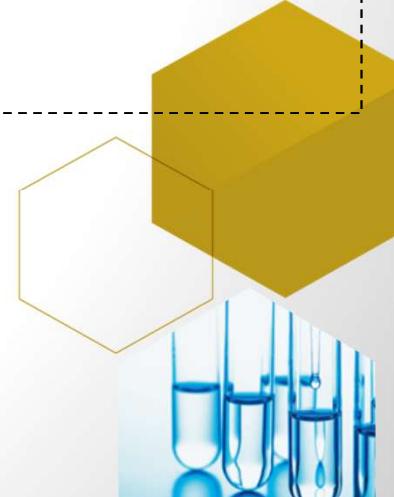
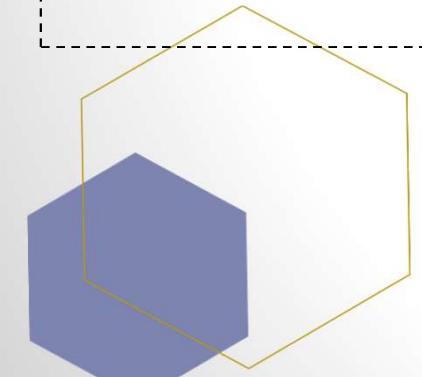




Summary of Financial Results

Key points on how to read the Company's business results

- Sales vary significantly between selling noble metals with chemicals and selling chemicals alone.
- Noble metals have a significant impact on sales because they are expensive and their prices fluctuate.



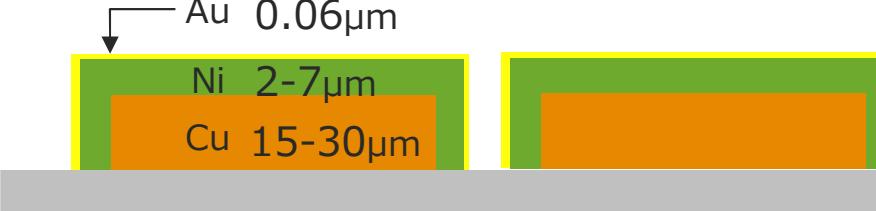
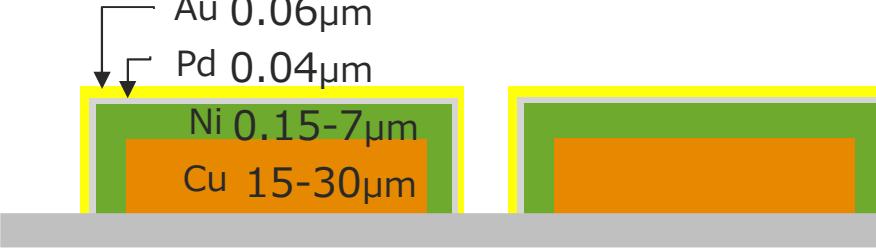
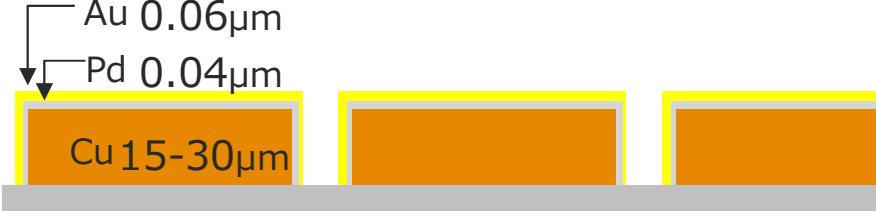
Plating Method

| Term | Applications | Features |
|----------------------------|-----------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------|
| Electrolytic plating | — | Plating method on metal surfaces with electric current |
| Pure gold plating | Printed circuit boards (CPU, GPU, etc.) for PCs, smartphones, etc. | High-purity gold plating |
| Hard gold plating | Connectors for smartphones, automotive, industrial machinery, etc. | Gold plating that is hardened with alloy components |
| Palladium (Pd) plating | Lead frames for PCs, automotive, industrial machinery, etc. | Used as an undercoat for gold plating. PPF stands for Pre Plated Lead frame. |
| Electroless plating | — | Plating method by chemical reaction without electric current |
| Immersion plating | Semiconductor memory (DRAM, NAND) Substrates with semiconductors for servers, PCs, smart phones, etc. | Plating method for forming by replacing metal on surface by utilizing solubility (ionization tendency) of each metal |
| Auto catalytic plating(Au) | Semiconductor Mounted Substrate CPU, GPU, etc. for servers, PCs, etc. | Plating method capable of forming thick coatings by utilizing chemical reaction with reducing agents |
| Auto catalytic plating(Pd) | Semiconductor Mounted Substrate for PC, server | Plating method capable of forming thick coatings by utilizing chemical reaction with reducing agents used as a base for gold plating |

Product Lineup

| Plating Methods | Applications | Product Lineup | |
|----------------------|--------------------------|---------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Electrolytic plating | Pure gold | | 1. Pure gold plating enabling uniform coating even on rough surfaces 2. Pure gold plating with higher hardness TEMPERESIST Series |
| | Hard gold (Alloy) | | Gold saving hard gold plating for micro connectors: OROBRIGHT BAR7 |
| | Palladium (Pd) | | Palladium plating for thin coating applicable to PPF: PALLABRIGHT NANO2 |
| Electroless plating | Immersion gold | | Immersion gold plating compatible with mid- to high-P Ni: IM-GOLD IB2X Immersion gold plating with less Ni corrosion: IM-GOLD CN Immersion gold plating without Ni plating: IM-GOLD PC IM-GOLD IB2X IM-GOLD CN IM-GOLD PC |
| | Auto catalytic gold | | Auto catalytic gold plating for thin coating using gold sulfite: HY-GOLD Auto catalytic gold plating for thin coating using gold cyanide: HY-GOLD CN HY-GOLD HY-GOLD CN |
| | Auto catalytic palladium | | Auto catalytic palladium plating for ENEPIG: NEO PALLABRIGHT 2 Direct auto catalytic palladium plating: NEO PALLABRIGHT DP NEO PALLABRIGHT 2 NEO PALLABRIGHT DP |
| Peripheral fields | | Base metals (copper, tin, nickel) Alloy plating, Post-treatment agents | |

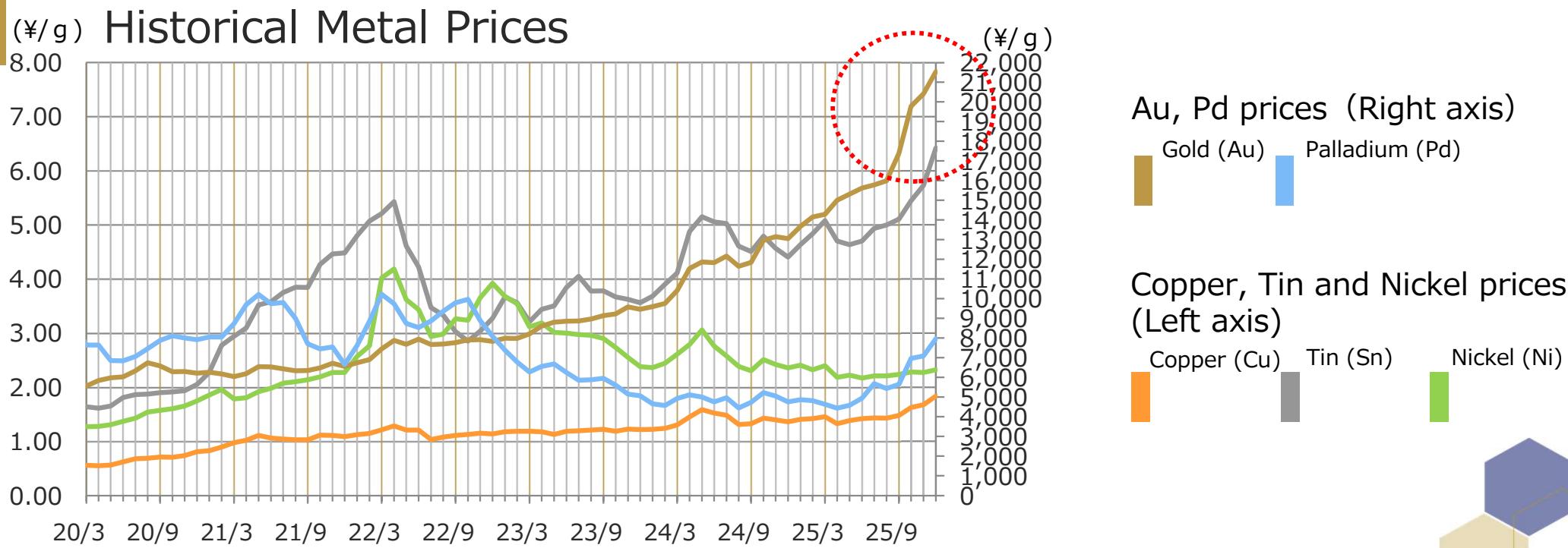
Plating Process Description

| Term | Description | Composition of plating |
|--------|-------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------|
| ENIG | Electroless Nickel Immersion Gold. Composition of plating is Cu-Ni-Au. |  <p>Au 0.06μm Ni 2-7μm Cu 15-30μm</p> |
| ENEPIG | Electroless Nickel Electroless Palladium Immersion Gold. Composition of plating is Cu-Ni-Pd-Au. |  <p>Au 0.06μm Pd 0.04μm Ni 0.15-7μm Cu 15-30μm</p> |
| DIG | Direct Immersion Gold. Since Ni plating is omitted, used for fine pitch compared to ENIG. Composition of plating is Cu-Au. |  <p>Au 0.06μm Cu 15-30μm</p> |
| EPIG | Electroless Palladium Immersion Gold. Composition of plating is Cu-Pd-Au. |  <p>Au 0.06μm Pd 0.04μm Cu 15-30μm</p> |

Au: gold, Pd: palladium, Ni: nickel, Cu: copper,
Micrometer (μm): one millionth of one meter

Market Conditions in the Electronic Components Industry

- Supported by expanding infrastructure demand for AI applications, demand for AI servers and data centers continued to remain strong. Meanwhile, demand for personal computers showed a steady recovery, while demand for consumer electronics such as smartphones and for industrial equipment including factory automation (FA) machinery showed only a gradual recovery.
- In the automotive electronics segment, although demand was supported by the wider adoption of advanced driver assistance systems (ADAS) and connected functionalities, growth in demand remained limited due to the impact of U.S. tariff measures and the reassessment of electric vehicle (EV) policies in Europe and the United States.



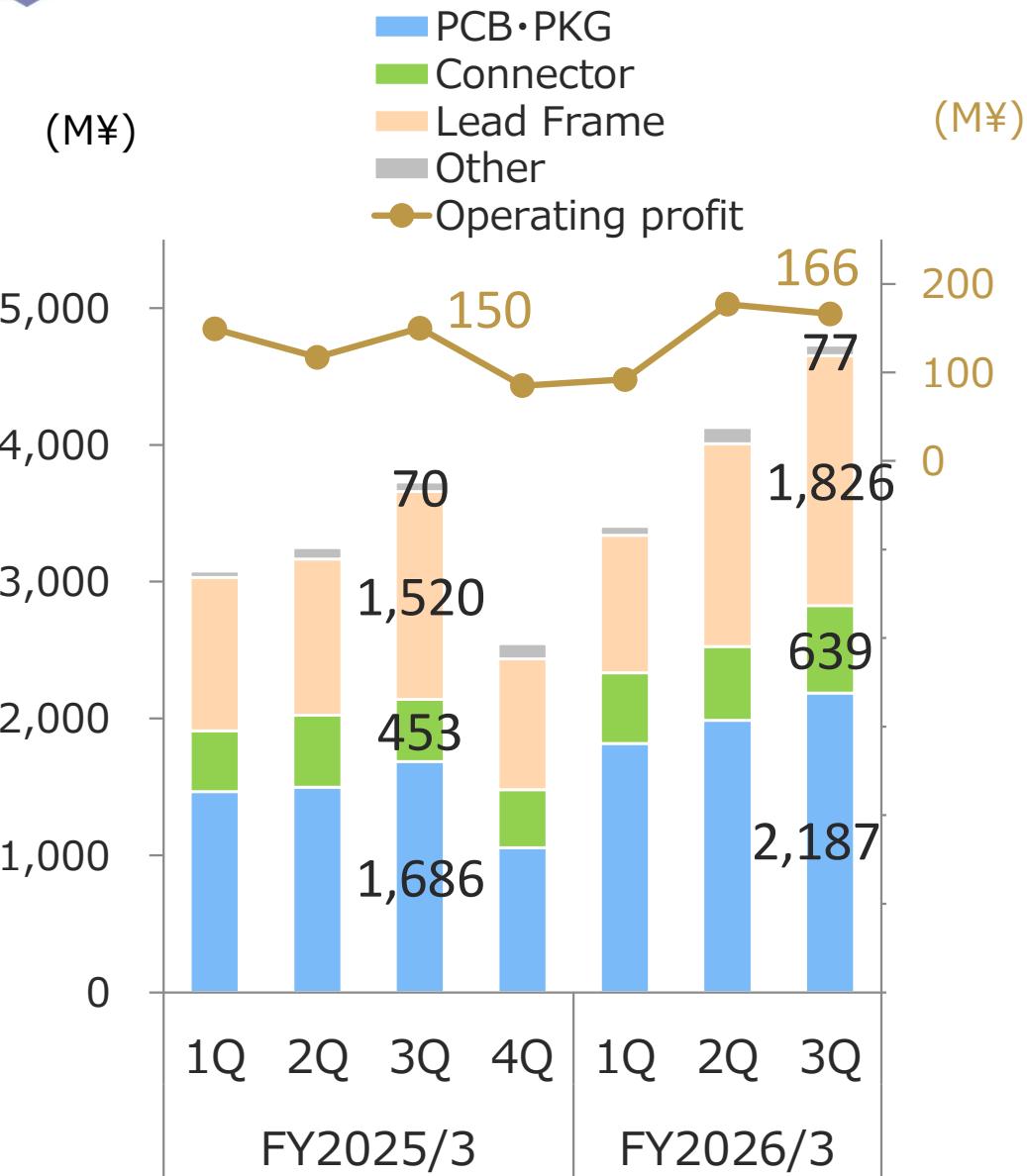
FY2026/3 3rd Quarter Financial Summary (cumulative)

Overview of Our Financial Results: Revenue Increased, Profit increased

- **Net Sales:** Driven by a recovery in consumer demand for smartphones and personal computers, as well as expanding generative AI-related demand, sales for semiconductor packages, modules, and memory applications remained solid. In addition, higher noble metal prices contributed to a year-on-year increase of 21.9%.
- **Operating Profit:** Gross profit increased due to sales expansion in new areas and higher volumes; however, expenses rose due to upfront investment in R&D. Consequently, operating profit increased by 4.8% year on year.
- **Quarterly Net Profit:** In addition to higher operating profit, gains on the sale of specified investment shares led to a year-on-year increase of 7.7%.

| (M¥) | FY2025/3 3Q | FY2026/3 | | | | | 3Q Progress ratio (Disclosed on 10/24) |
|-------------------------------|----------------|----------|-------|--------|--------|--------------------------------|----------------------------------------------|
| | | 1Q | 2Q | 3Q | Total | Increase/ Decrease ratio | |
| Net sales | 10,061 | 3,406 | 4,129 | 4,730 | 12,267 | +21.9% | 87.6% |
| Operating profit | 417 | 92 | 178 | 166 | 437 | +4.8% | 85.8% |
| Ordinary profit | 563 | 184 | 193 | 242 | 620 | +10.1% | 92.6% |
| Net profit | 1,331 | 135 | 489 | 810 | 1,434 | +7.7% | 98.9% |
| Net profit per share (Yen) | 230.83 | 23.40 | 84.60 | 140.00 | 248.10 | – | – |

Net sales and operating income (Quarterly basis)

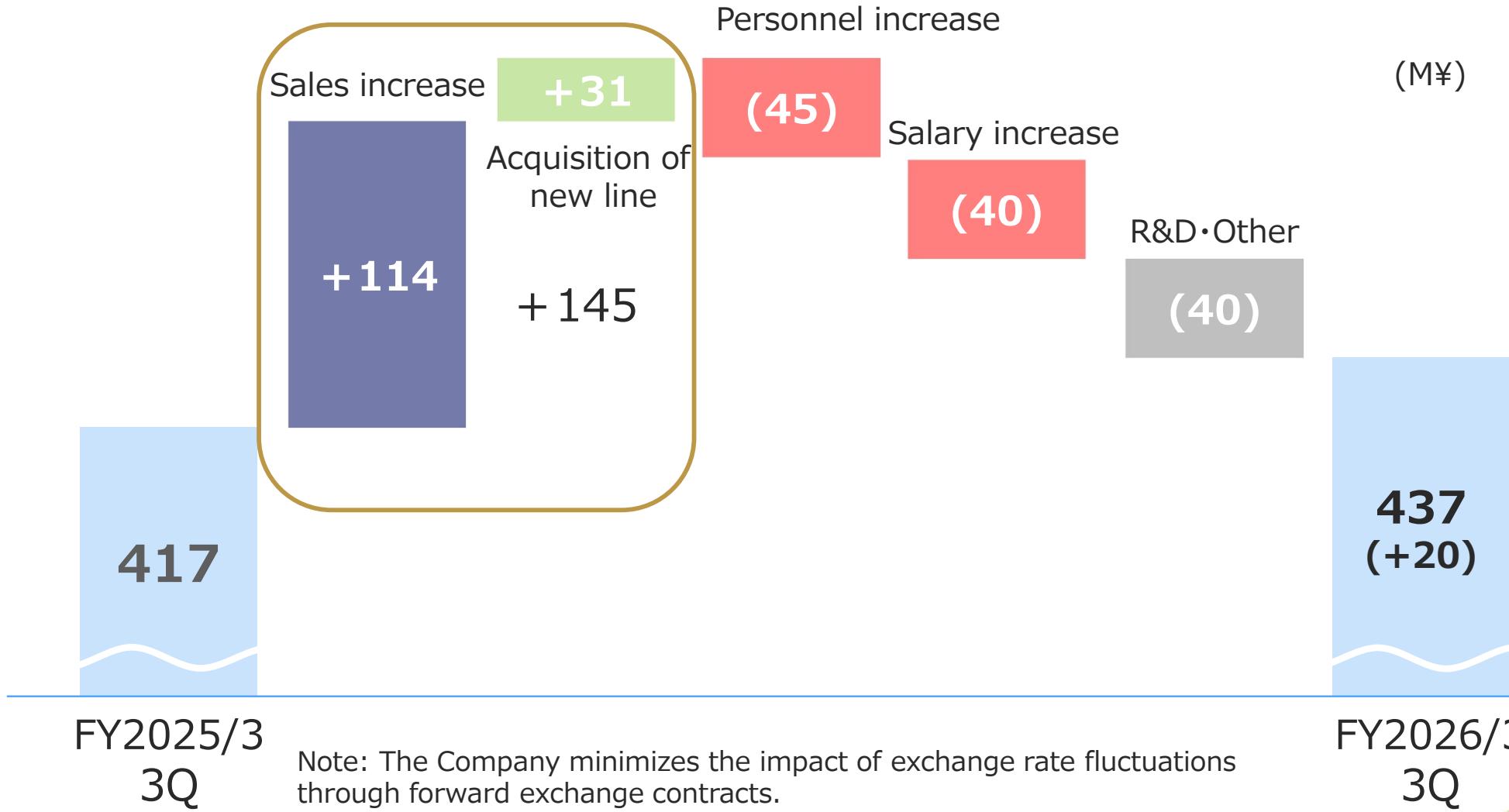


Overview by Category

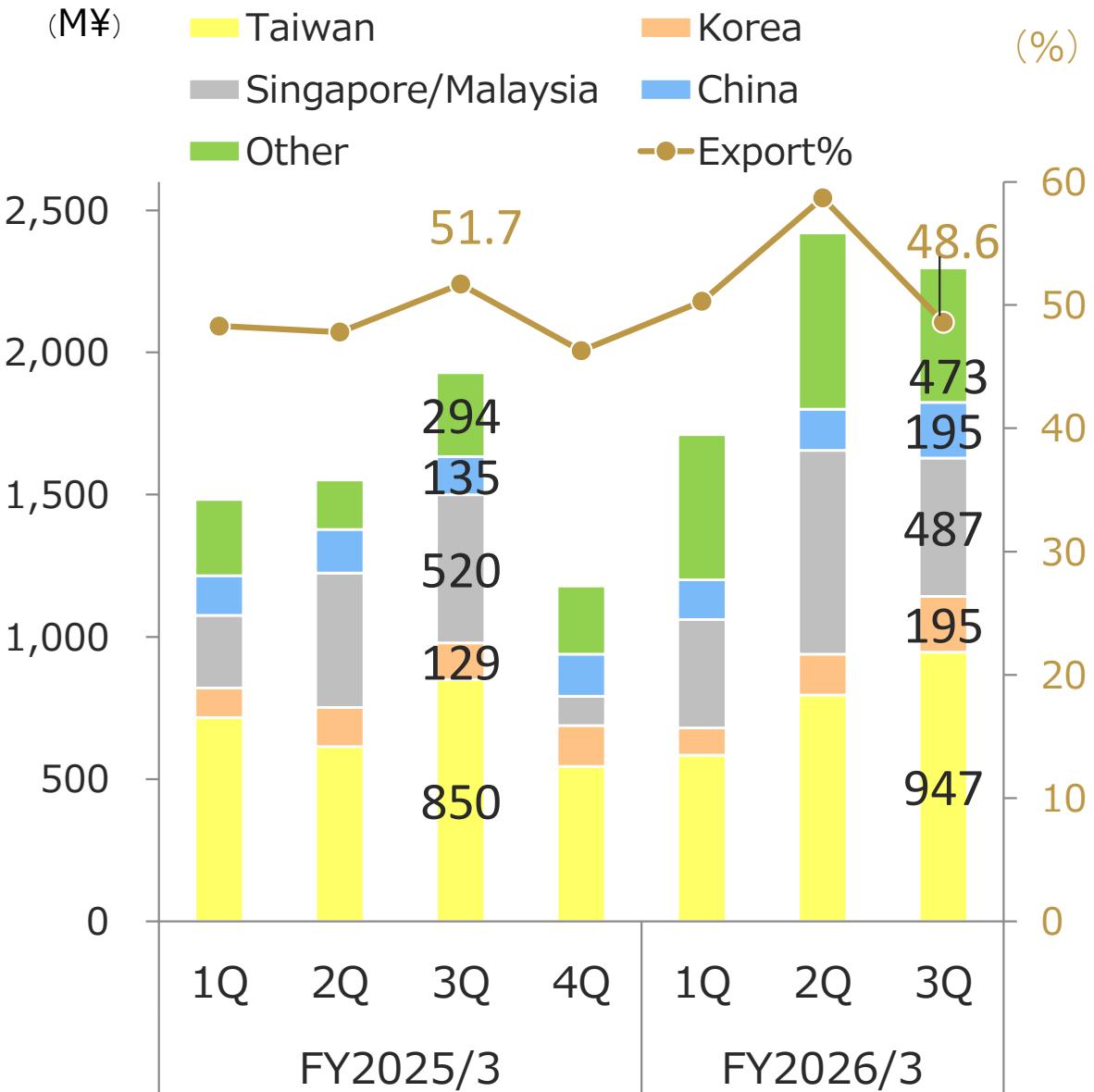
- Plating chemicals for printed circuit boards and semiconductor substrates
Sales increased, driven by recovery in consumer electronics (smartphones/PCs) and solid demand for generative AI-related semiconductor packages, optical modules, and memory.
- Plating chemicals for connectors
Sales increased as recovery in smartphones and industrial equipment offset sluggish automotive demand.
- Plating chemicals for lead frame
Sales increased, supported by solid consumer demand and higher noble metal prices, despite weak automotive demand.

YoY Operating Profit breakdown

- Higher sales volumes driven by demand recovery, together with increased orders for new production lines, contributed to higher profits.
- Profit growth was secured by absorbing higher costs from continued investment in human capital and R&D.



Net Sales by Export Regions (Quarterly basis)



Reason for Increase/Decrease

Taiwan

Despite inventory adjustments in automotive applications, revenue increased due to steady demand for AI server-related optical modules and consumer lead frames.

Singapore·Malaysia

Revenue decreased due to temporary inventory adjustments by customers.

Other

Increased demand for PC- and server-related packaging applications in the Philippines

FY2026/3 3rd Quarter Financial Summary (cumulative)

- Solid performance is expected in servers and data centers, supported by expanding AI infrastructure demand
- Automotive sector faces prolonged inventory adjustment risks amid slowing EV demand
- Revised the full-year forecasts for net sales and profits, reflecting recent performance and fluctuations in noble metal prices
- Incorporated additional disposals of specified investment shares
- Dividends: Year-end dividend of JPY 137 per share (+JPY 74); annual dividend of JPY 200 per share (Flexible shareholder returns will be continued alongside the reduction of specified investment shares under the Medium-Term Management Plan)

| (M¥) | FY2025/3 | FY2026/3 | Y oY | Disclosed Oct 24 |
|-------------------------------------|----------|----------|--------|------------------|
| Net sales | 12,611 | 17,500 | +38.8% | +25.0% |
| Operating profit | 502 | 540 | +7.4% | +5.9% |
| Ordinary profit | 657 | 730 | +11.0% | +9.0% |
| Gain on Specified investment shares | 1,512 | 1,650 | +9.1% | +22.2% |
| Net profit | 1,579 | 1,750 | +10.8% | +20.7% |
| Dividend (¥) | 126 | 200 | +74 | +74 |
| ROE | 11.3% | 10.6% | — | — |

Progress in sales of specified investment shares

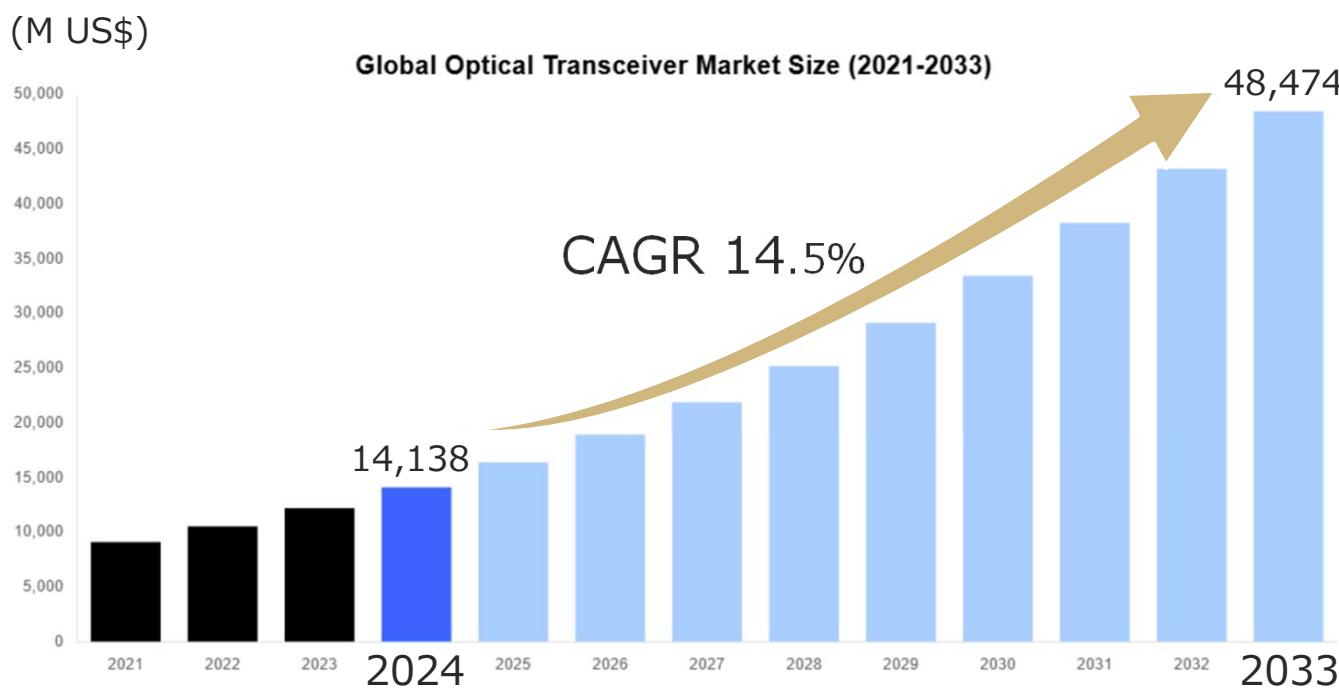
- Regarding our specified investment shares, the company has set a target in its medium-term management plan (FY2025-2027) to reduce the ratio of policy holdings to net assets to below 20%.
- The share sale proceeded in accordance with the announcement released on October 24, 2025, titled "(Update on Disclosed Matter) Notice Regarding Recording of Gain on Sale of Investment Securities (Extraordinary Income)" and was completed as scheduled.
- Taking market conditions into account, the Company plans to conduct additional disposals.

| | 2024 Dec | 2025 Mar | 2025 Jun | 2025 Sep | 2025 Dec |
|-------------------------------------------|-------------|-------------|-------------|-------------|-------------|
| Amount sold * (million yen) | 553 | 275 | – | 493 | 933 |
| Market value of shares held (million yen) | 7,108 | 5,974 | 6,740 | 8,416 | 9,308 |
| Net assets (million yen) | 14,149 | 13,594 | 13,891 | 15,566 | 16,659 |
| Percentage of net assets (%) | 50.2 | 43.9 | 48.5 | 54.1 | 55.9 |

* Amount sold during the relevant quarter

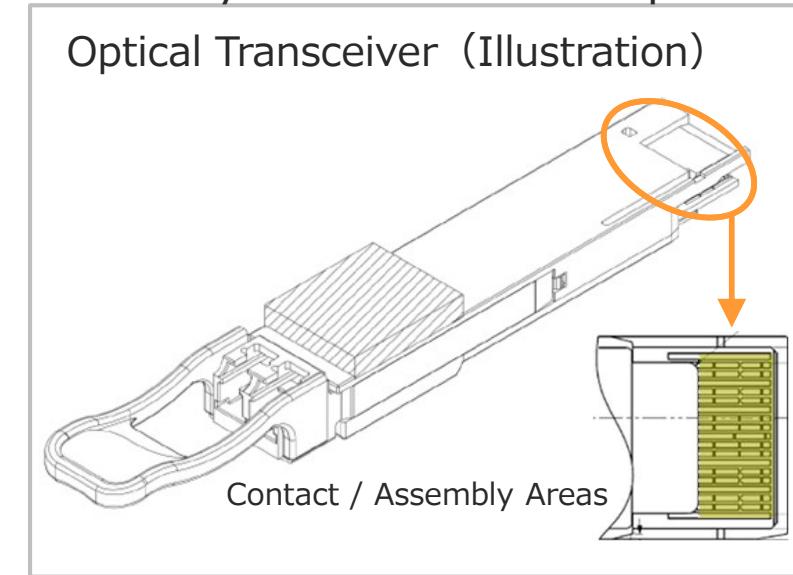
Topic: Expanding Growth Opportunities in Optical Transceiver Applications

- Optical transceivers for AI servers require high reliability for long-term stable operation, and the Company's electroless Pd (palladium) plating technology — long regarded as a core strength—is increasingly being recognized as an industry standard, driving expanding customer discussions and adoption.
- Strengthen electroless Pd plating as a core competence to capture growing AI server demand and drive sustainable share expansion.

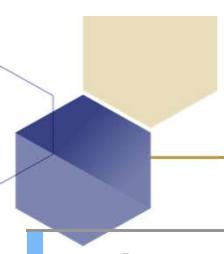


Source : Straits Research Analysis
https://straitsresearch.com/vertex/insights/optical-transceiver-market/global?utm_source=chatgpt.com

Electroless plating is widely used, particularly in connector components



Source : QSFP-DD-Hardware-Rev7.1 (P66,69)



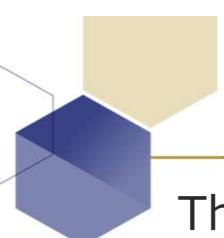
Appendix: Company Introduction

History

- July 1971 Establishment of JAPAN PURE CHEMICAL CO.,LTD.
- November 1999 Implementation of MBO
- December 2002 JASDAQ market listing
- March 2004 Listing on TSE Second Section
- March 2005 Listing on TSE First Section
- February 2019 Establishment of General incorporated foundation, JPC Scholarship Foundation
- April 2020 Certification as public interest incorporated foundation, JPC Scholarship Foundation
- April 2022 Moved to the Prime Market on TSE

Business Summary

- Fine chemical company supplying electronic materials which support development of the electronic components industry
- Top-class share in the worldwide market by narrowing the business targets to noble metal plating process
- Construct sales and technical support systems that can respond quickly to the rapidly changing industry
- Fab-light company that does not have large-scale manufacturing plants
- Provide technology to minimize the amount of noble metals used for connecting electronic components and contribute to effective use of mineral resources



Disclaimer

The materials used in the preparation of forecasts of results and predictions are based upon predicted trends in the industries related to the Company's operations. Accordingly, economic conditions both in Japan and overseas, fluctuations in exchange rates and other factors may influence forecasts of results. The predictions and forecasts made are based upon the information available as of December 31, 2025.

There are a number of factors that cannot be predicted with certainty that may have an influence on these forecasts, including market conditions, competitors' actions, the performance of newly introduced products and services, and the global IT market and related markets. Accordingly, actual results may vary significantly from the forecasts presented in this document.

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Corporate Planning Division

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